



Product Change Notification

110118 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 110118 - 00
Change Title: Boxed Intel® Core™ i7-970 Processor, PCN 110118-00, Product Design, Impeller Fan Blade Thickness Reduction and Hub Perforations

Date of Publication: June 21, 2010

Key Characteristics of the Change:

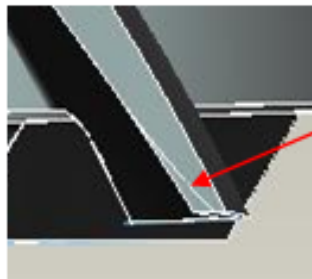
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jul 05, 2010
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Description of Change to the Customer:

In order to improve acoustic quality, the thickness of the impeller trailing edge of the fan blades has been thinned to 0.3mm. Perforations have been added to the impeller hub design to further improve fan performance characteristics. Perforations are located under the hologram label.



Reduction of blade thickness at the trailing edge



Perforated impeller without label



Perforated impeller with label

Customer Impact of Change and Recommended Action:

There is no expected change or impact to customers.

Products Affected / Intel Ordering Codes:

Marketing Name	Processor#	Frequency	Stepping	Product Code	S-Spec	MM#
Intel® Core™ Processor	i7-970	3.20 GHz	B1	BX80613I7970	S LBVF	908321

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

June 21, 2010

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Originally Published PCN